

APPARATUS FOR IMMOBILIZING A SOLID SOLDER ELEMENT
TO A CONTACT SURFACE OF INTEREST

5

ABSTRACT OF THE DISCLOSURE

A solid solder element (106), such as a solder perform, is attached onto a contact surface of interest (102), such as a heat sink using an adhesive material (104). Placement of the adhesive material overcomes alignment and registration issues that may interfere with good contact to components (108), such as transistors, during the manufacturing/assembly process, such as a reflow process.

10